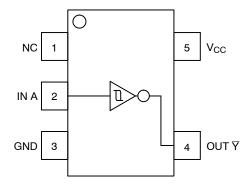
Single Inverter with Schmitt Trigger

The NL17SZ14 is a single inverter with Schmitt trigger in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive.

Features

- Tiny SOT-353 and SOT-553 Packages
- Source/Sink 24 mA at 3.0 V
- Over-Voltage Tolerant Inputs and Outputs
- Pin For Pin with NC7SZ14
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Chip Complexity: FET = 20
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant





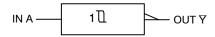


Figure 2. Logic Symbol



ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS







SOT-553 XV5 SUFFIX CASE 463B



LA = Device Code M = Date Code*

= Date Code*

= Pb-Free Package

(*Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT				
1	NC			
2	IN A			
3	GND			
4	OUT Y			
5	V _{CC}			

A Input	Y Output
L H	HL
Н	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Charact	teristics	Value	Units
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \leq V_I \leq +7.0$	V
Vo	DC Output Voltage	Output in High or LOW State (Note 1)	$-0.5 \leq V_O \leq +7.0$	V
I _{IK}	DC Input Diode Current	V _I < GND	-50	mA
I _{OK}	DC Output Diode Current	V _O < GND	-50	mA
Ι _Ο	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin		±100	mA
I _{GND}	DC Ground Current per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
PD	Power Dissipation in Still Air	SOT-353 SOT-553	186 135	mW
θ_{JA}	Thermal Resistance	SOT-353 SOT-553	350 496	°C/W
TL	Lead Temperature, 1 mm from Case for	10 Seconds	260	°C
TJ	Junction Temperature under Bias		+150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD	ESD Classification	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	Class 2 Class C N/A	
ILATCHUP	Latchup Performance Above V_{CC} and E	Below GND at 125°C (Note 5)	±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.

Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
Tested to JESD22-C101-A.

5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Мах	Units
V _{CC}	Supply Voltage Operating Data Retention Only		1.65 1.5	5.5 5.5	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage (High or LOW State)		0	5.5	V
T _A	Operating Free-Air Temperature		-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 2.5 V \pm 0.2 V V_{CC} = 3.0 V \pm 0.3 V V_{CC} = 5.0 V \pm 0.5 V $	0 0 0	No Limit No Limit No Limit	ns/V

DC ELECTRICAL CHARACTERISTICS

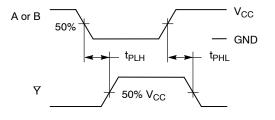
			V _{CC}	TA	T _A = 25°C		–55°C ≤ T _A ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
$V_T +$	Positive Input		1.65	0.6	1.0	1.4	0.6	1.4	V
	Threshold Voltage		2.3	1.0	1.5	1.8	1.0	1.8	
			2.7	1.2	1.7	2.0	1.2	2.0	
			3.0	1.3	1.9	2.2	1.3	2.2	
			4.5	1.9	2.7	3.1	1.9	3.1	
			5.5	2.2	3.3	3.6	2.2	3.6	
V _T -	/T – Negative Input		1.65	0.2	0.5	0.8	0.2	0.8	V
	Threshold Voltage		2.3	0.4	0.75	1.15	0.4	1.15	
			2.7	0.5	0.87	1.4	0.5	1.4	
			3.0	0.6	1.0	1.5	0.6	1.5	
			4.5	1.0	1.5	2.0	1.0	2.0	
			5.5	1.2	1.9	2.3	1.2	2.3	
V _H Input Hys Voltage	Input Hysteresis		1.65	0.1	0.48	0.9	0.1	0.9	V
	Voltage		2.3	0.25	0.75	1.1	0.25	1.1	
			2.7	0.3	0.83	1.15	0.3	1.15	
			3.0	0.4	0.93	1.2	0.4	1.2	
			4.5	0.6	1.2	1.5	0.6	1.5	
			5.5	0.7	1.4	1.7	0.7	1.7	
V _{OH}	High-Level Output	I _{OH} = -100 μA	1.65 to 5.5	V _{CC} - 0.1	V _{CC}		V _{CC} - 0.1		V
	Voltage V _{IN} = V _{IH} or V _{IL}	I _{OH} = –3 mA	1.65	1.29	1.52		1.29		
		I _{OH} = -8 mA	2.3	1.9	2.1		1.9		
		I _{OH} = -12 mA	2.7	2.2	2.4		2.2		
		I _{OH} = -16 mA	3.0	2.4	2.7		2.4		
		I _{OH} = -24 mA	3.0	2.3	2.5		2.3		
		I _{OH} = -32 mA	4.5	3.8	4.0		3.8		
V _{OL}	Low-Level Output	I _{OL} = 100 μA	1.65 to 5.5		0.0	0.1		0.1	V
	Voltage V _{IN} = V _{IH} or V _{IL}	I _{OL} = 4 mA	1.65		0.08	0.24		0.24	
		I _{OL} = 8 mA	2.3		0.2	0.3		0.3	
		I _{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I _{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I _{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I _{OL} = 32 mA	4.5	-	0.42	0.55		0.55	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μA
I _{OFF}	Power Off Leakage Current	$V_{IN} = 5.5 V \text{ or}$ $V_{OUT} = 5.5 V$	0			1		10	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V or GND	5.5			1		10	μΑ

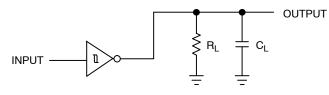
			V _{cc}	T _A = 25°C		$-55^{\circ}C \leq T_{A} \leq 125^{\circ}C$			
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t _{PLH} t _{PHL}	Propagation Delay (Figure 3 and 4)	$R_L = 1 M\Omega, C_L = 15 pF$	$1.65 \\ 1.8 \\ 2.5 \pm 0.2 \\ 3.3 \pm 0.3 \\ 5.0 \pm 0.5$	2.0 2.0 1.0 1.0 0.5	9.1 7.6 5.0 3.7 3.1	15 12.5 9.0 6.3 5.2	2.0 2.0 1.0 1.0 0.5	15.6 13 9.5 6.5 5.5	ns
		R_L = 500 Ω, C_L = 50 pF	$\begin{array}{c} 3.3 \pm 0.3 \\ 5.0 \pm 0.5 \end{array}$	1.5 0.8	4.4 3.7	7.2 5.9	1.5 0.8	7.5 6.2	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter Condition		Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	>4.0	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	10 MHz, $V_{CC} = 3.3$ V, $V_I = 0$ V or V_{CC} 10 MHz, $V_{CC} = 5.5$ V, $V_I = 0$ V or V_{CC}	25 30	pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.





A 1–MHz square input wave is recommended for propagation delay tests.

Figure 3. Switching Waveform

DEVICE ORDERING INFORMATION

Figure 4. Test Circuit

Device Order Number	Package Type	Tape and Reel Size [†]
NL17SZ14DFT2G	SC-88A/SC-70-5/SOT-353 (Pb-Free)	3000 / Tape & Reel
NLV17SZ14DFT2G*	SC-88A/SC-70-5/SOT-353 (Pb-Free)	3000 / Tape & Reel
NL17SZ14XV5T2G	SOT-553 (Pb-Free)	4000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

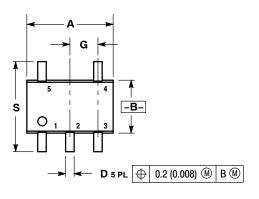
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

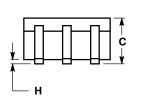
NL17SZ14

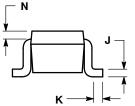
PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353) CASE 419A-02

ISSUE L



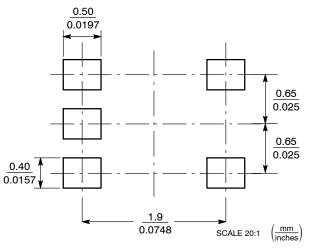




NOTES:
DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: INCH.
419A-01 OBSOLETE. NEW STANDARD 419A-02.
DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
Κ	0.004	0.012	0.10	0.30	
Ν	0.008	REF	0.20	REF	
S	0.079	0.087	2.00	2.20	

SOLDER FOOTPRINT*

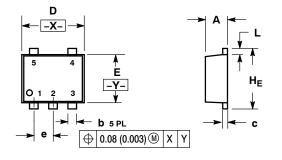


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NL17SZ14

PACKAGE DIMENSIONS

SOT-553 **XV5 SUFFIX** CASE 463B **ISSUE B**



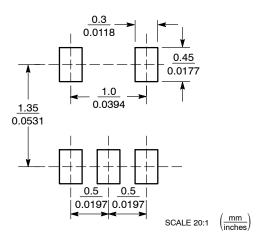
NOTES DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM 1. 2.

3.

THICKNESS OF BASE MATERIAL.

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
Е	1.10	1.20	1.30	0.043	0.047	0.051
е	0.50 BSC				0.020 BSC)
L	0.10	0.20	0.30	0.004	0.008	0.012
ΗE	1.50	1.60	1.70	0.059	0.063	0.067

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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